

ABSTRACT

In order to prevent short-circuiting when a chip component is brazed to pads of a conductive wiring layer, a hybrid semiconductor circuit includes the chip component with terminal electrodes formed at both ends, a first conductive wiring layer on which the pads are provided such that they correspond to the terminal electrodes, and an overcoat resin that covers the first conductive wiring layer excluding the pads. The terminal electrodes of the chip component are adhered to the pads by a conductive adhesive and an insulating adhesive is provided between the pads.